



# Product Change Notification

**Change Notification #:** 115305-00  
**Change Title:** Intel® Compute Module HNS2600KPR  
PCN115306-00, Product Material,  
Replacement of BMC DDR3 chip  
**Date of Publication:** February 15, 2017

## Key Characteristics of the Change:

Product Material

## Forecasted Key Milestones:

**Date Customer Must be Ready to Receive Post-Conversion Material:** \* March 06, 2017

\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

## Description of Change to the Customer:

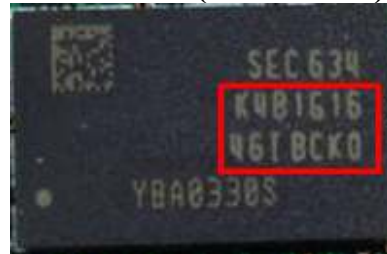
Intel is implementing the following change to Intel® Compute Module HNS2600KPR:

Intel is replacing the current BMC DDR3 memory chip K4B1G1646G-BCH9 (G38649-001) (end of life) with new K4B1G1646I-BCK0 (J37656-001). Intel reports validation completed with passing results. The replacement component is identical in form, fit and function.

**Current DDR3 (G38649-001)**



**New DDR3 (J37656-001)**



## Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason, Intel recommends that the customers perform a standard level of evaluation.

Please contact your local Intel Sales Office or Distributor if you require more information.

## Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
Intel® Compute Module HNS2600KPR	HNS2600KPR	943787	H94936-004	H13888-371	H94936-005	H13888-372

## PCN Revision History:

**Date of Revision:**

February 15, 2017

**Revision Number:**

00

**Reason:**

Originally Published PCN



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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